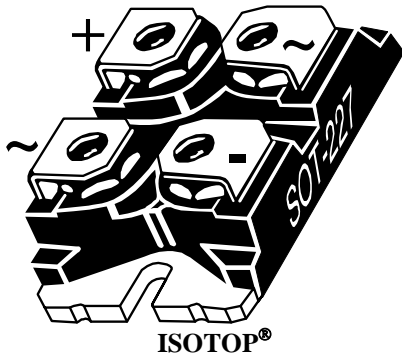
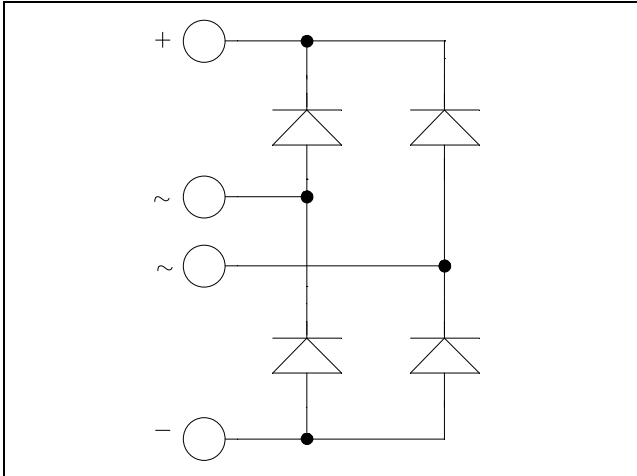


## ISOTOP<sup>®</sup> SiC Diode Full Bridge Power Module

$V_{RRM} = 600V$   
 $I_C = 6A @ T_C = 100^{\circ}C$



### Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

### Features

- **SiC Schottky Diode**
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature Independent switching behavior
  - Positive temperature coefficient on VF
- ISOTOP<sup>®</sup> Package (SOT-227)
- Very low stray inductance
- High level of integration

### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
$V_R$	Maximum DC reverse Voltage	600	V
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage		
$I_{F(AV)}$	Maximum Average Forward Current	6	A
$I_{FSM}$	Non-Repetitive Forward Surge Current	210	

*Note: Duty cycle = 50%,  $T_C = 100^{\circ}C$  for  $I_{F(AV)}$  and  $T_C = 25^{\circ}C$  for  $I_{FSM}$ .*

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

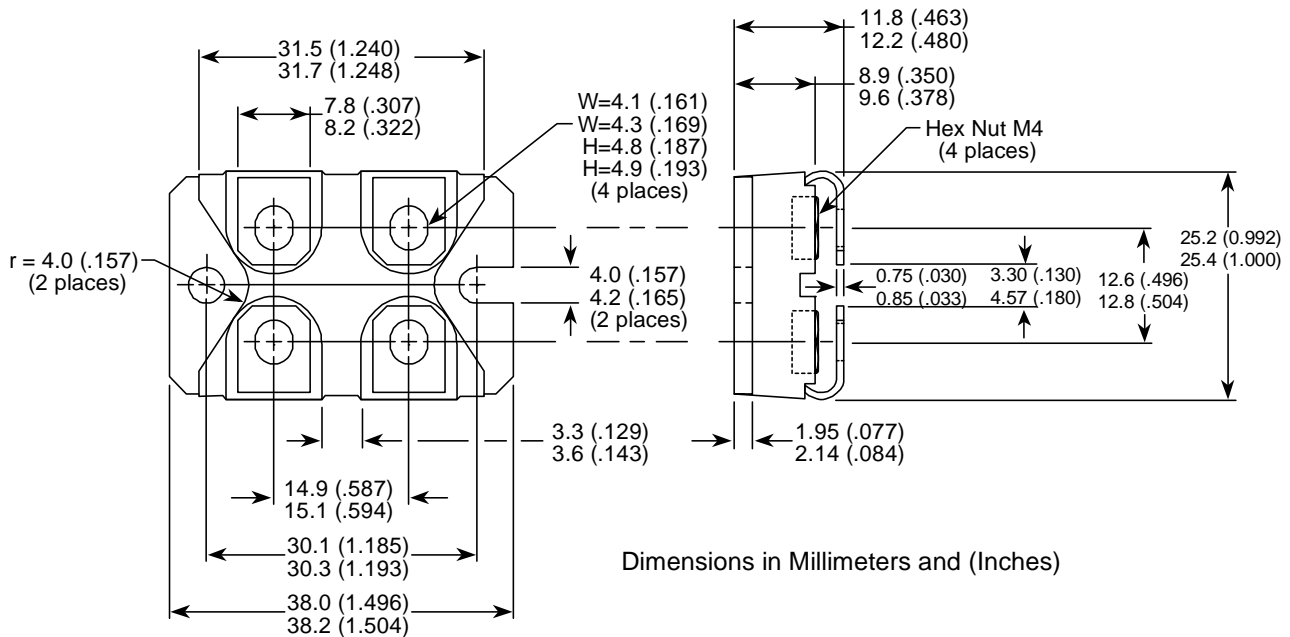
All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

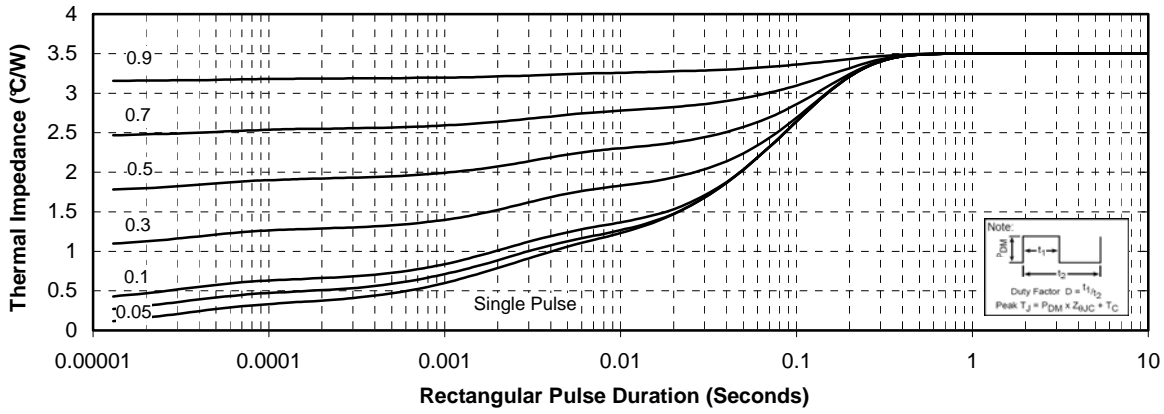
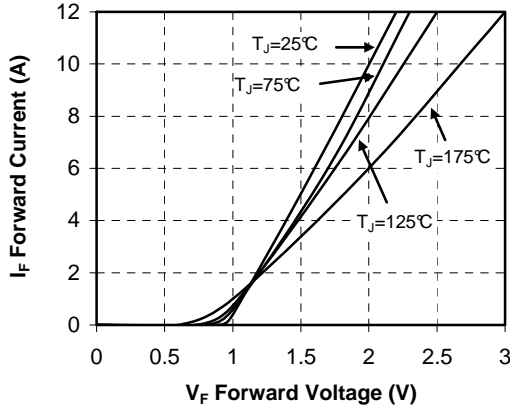
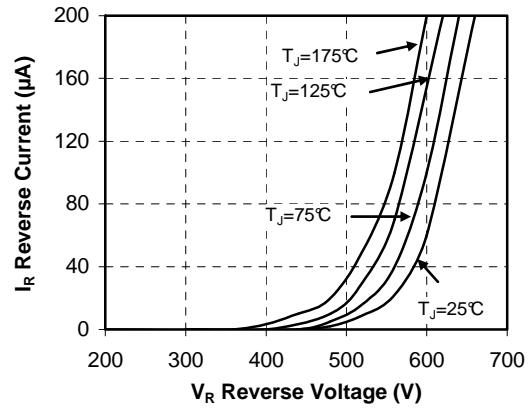
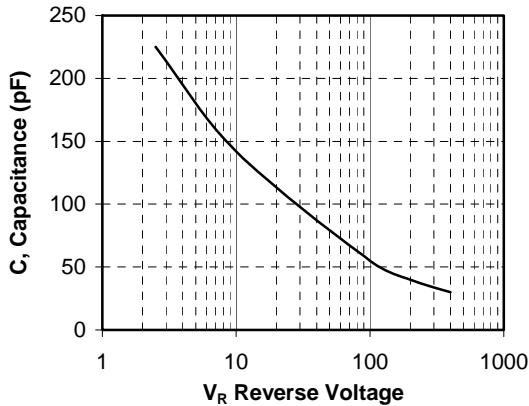
**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$V_F$	Diode Forward Voltage	$I_F = 6\text{A}$	$T_j = 25^\circ\text{C}$		1.6	1.8	V
			$T_j = 175^\circ\text{C}$		2.0	2.4	
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$		50	200	$\mu\text{A}$
			$T_j = 175^\circ\text{C}$		100	1000	
$Q_C$	Total Capacitive Charge	$I_F = 6\text{A}, V_R = 600\text{V}$ $di/dt = 500\text{A}/\mu\text{s}$		17		nC	
C	Total Capacitance	$f = 1\text{MHz}, V_R = 200\text{V}$		40		pF	
		$f = 1\text{MHz}, V_R = 400\text{V}$		30			

**Thermal and package characteristics**

Symbol	Characteristic	Min	Typ	Max	Unit
$R_{thJC}$	Junction to Case Thermal resistance			3.5	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Junction to Ambient			20	
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$ , $I_{isol} < 1\text{mA}$ , 50/60Hz	2500			V
$T_J, T_{STG}$	Storage Temperature Range	-55		175	$^\circ\text{C}$
$T_L$	Max Lead Temp for Soldering: 0.063" from case for 10 sec			300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

**SOT-227 (ISOTOP<sup>®</sup>) Package Outline**


**Typical Performance Curve**
**Maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration**

**Forward Characteristics**

**Reverse Characteristics**

**Capacitance vs. Reverse Voltage**


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Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 6,939,743 7,352,045 5,283,201 5,801,417 5,648,283 7,196,634 6,664,594 7,157,886 6,939,743 7,342,262 and foreign patents. U.S and Foreign patents pending. All Rights Reserved.